

CHIP TRANSFER PROCESS

ABSTRACT

The invention relates to a process for transferring chips from tiles arranged on a support substrate onto a receiver substrate, which comprises:

- forming a substrate (10), known as the pseudo-donor substrate, comprising the support substrate (2) and the tiles (1), in which two adjacent tiles are separated by a first distance (d_1),
- performing chemical-mechanical polishing of the tiles,
- forming an embrittlement area in at least a part of the tiles so as to delimit a respective chip,
- bonding the pseudo-donor substrate to the receiver substrate via the tiles,
- detaching the tiles along the embrittlement area so as to transfer a respective chip onto the receiver substrate, with two adjacent chips being separated by a second distance greater than the first distance (d_1),
- prior to bonding, localized roughening of the surface of the tiles and/or of the receiver substrate to render areas of said surface incapable of bonding, so as to prevent the transfer of chips into said areas.

Figure for the abstract: Fig. 2